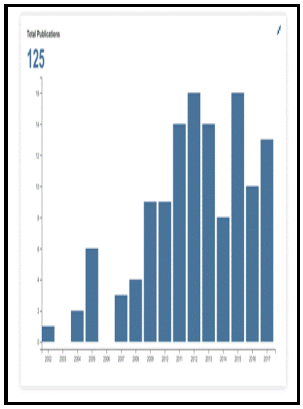
Electron-beam, X-ray, EUV, and ion-beam submicrometer lithographies for manufacturing VI - 11-13 March 1996, Santa Clara, California

SPIE - Fabrication & Design of Resonant Microdevices (Micro and Nano Technologies)



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standard soft lithography: Topics by Science.gov

The image at left was taken on May 23, 2013 at an incidence angle of 56 degrees; the image at right was taken on August 21, 2014 at an incidence angle of 5 degrees. The soft-mold reverse nanoimprint lithography also leaves little or no residual layer, affording good isolation of the nanostructures.

ultraviolet projection lithography: Topics by Science.gov

High moment soft amorphous CoFeZrRe thin-film materials. The latter phenomenon is isolated from the others by dissolving contaminants in cyclohexane and determining absorption spectra from 2100A to 3600A.

ultraviolet projection lithography: Topics by Science.gov

Here, we describe a simple process of direct nanoimprint lithography using palladium benzylthiolate, a versatile metal-organic ink, which not only leads to the formation of hierarchical patterns but also is amenable to layer-by-layer stacking of the metal over large areas. The properties of the electromagnetic wave were measured using a THz time-domain spectrometer.

Nanopackaging: Nanotechnologies and Electronics Packaging

Crystal Growth Semiconductor wafers are cut from large crystals of the semiconducting material.

x

It is anticipated that the lifetime of a single template for patterned media or mask for semiconductor will be on the order of 104 - 105imprints. This means that the gauge reading is absolute; it does not include the pressure of the outside atmosphere. Techniques for 3D micromachining by direct lithography using x-rays are developed.

Nanopackaging: Nanotechnologies and Electronics Packaging

The standard electron microscope lacks several key lithographic system components that can be added at varying costs. These same density improvements result in a chip or circuit that requires less power to operate.

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